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(54) HOT MELT ADHESIVE COMPOSITION**(57)Abstract:**

PURPOSE: To obtain a hot melt adhesive having a long open time, does not cause a moisture-permeable olefin resin film to undergo exudation and has a low melt viscosity.

CONSTITUTION: This composition comprises 100 pts.wt. butene-1 homopolymer and/or butene-1 copolymer, 40-300 pts.wt. tackifying resin, and 10-100 pts.wt. unsaturated hydrocarbon oligomer having a flow point of -80 to 30° C and desirably having 4-14 carbon atoms.

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